

Is Now Part of



ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at www.onsemi.com

Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild guestions@onsemi.com.

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officer



March 2015

FGH40N60UFD 600 V, 40 A Field Stop IGBT

Features

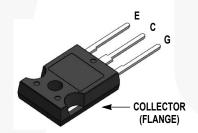
- · High Current Capability
- Low Saturation Voltage: V_{CE(sat)} = 1.8 V @ I_C = 40 A
- · High Input Impedance
- · Fast Switching
- RoHS Compliant

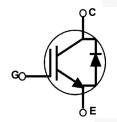
Applications

· Solar Inverter, UPS, Welder, PFC, Microwave Oven, Telecom, ESS

General Description

Using novel field stop IGBT technology, Fairchild's field stop IGBTs offer the optimum performance for solar inverter, UPS, welder, microwave oven, telecom, ESS and PFC applications where low conduction and switching losses are essential.





Absolute Maximum Ratings

Symbol	Description	n	Ratings	Unit
V _{CES}	Collector to Emitter Voltage		600	V
V _{GES}	Gate to Emitter Voltage		± 20	V
GES	Transient Gate-to-Emitter Voltage		± 30	V
lo	Collector Current	@ T _C = 25°C	80	A
IC	Collector Current	@ T _C = 100°C	40	Α
I _{CM (1)}	Pulsed Collector Current	@ T _C = 25°C	120	Α
P _D	Maximum Power Dissipation	@ T _C = 25°C	290	W
. п	Maximum Power Dissipation	@ T _C = 100°C	116	W
TJ	Operating Junction Temperature		-55 to +150	°C
T _{stg}	Storage Temperature Range		-55 to +150	°C
TL	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 second		300	°C

Notes:1: Repetitive rating: Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction to Case	-	0.43	°C/W
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case	-	1.45	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	-	40	°C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FGH40N60UFDTU	FGH40N60UFD	TO-247	Tube	N/A	N/A	30

Electrical Characteristics of the IGBT $T_C = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	eteristics					
BV _{CES}	Collector to Emitter Breakdown Voltage	V _{GE} = 0 V, I _C = 250 μA	600	-	-	V
$\frac{\Delta BV_{CES}}{\Delta T_J}$	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0 \text{ V}, I_{C} = 250 \mu\text{A}$	-	0.6	-	V/°C
I _{CES}	Collector Cut-Off Current	V _{CE} = V _{CES} , V _{GE} = 0 V	-	-	250	μА
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0 V$	-	-	±400	nA
On Charac	teristics					
V _{GE(th)}	G-E Threshold Voltage	I_C = 250 μ A, V_{CE} = V_{GE}	4.0	5.0	6.5	V
		I _C = 40 A, V _{GE} = 15 V	-	1.8	2.4	V
V _{CE(sat)}	Collector to Emitter Saturation Voltage	I _C = 40 A, V _{GE} = 15 V, T _C = 125°C	-	2.0	-	V
Dynamic C	Characteristics					
C _{ies}	Input Capacitance		-	2110	-	pF
C _{oes}	Output Capacitance	$V_{CE} = 30 \text{ V}, V_{GE} = 0 \text{ V},$ f = 1 MHz	-	200	-	pF
C _{res}	Reverse Transfer Capacitance	1 - 1 Wil 12	-	60	-	pF
Switching	Characteristics					
t _{d(on)}	Turn-On Delay Time			24	-	ns
t _r	Rise Time		-	44	-	ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 400 \text{ V}, I_{C} = 40 \text{ A},$	-	112	-	ns
t _f	Fall Time	$R_G = 10 \Omega, V_{GE} = 15 V,$	-	30	60	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 25°C	-	1.19	-	mJ
E _{off}	Turn-Off Switching Loss		-	0.46	-	mJ
E _{ts}	Total Switching Loss		-	1.65	- /	mJ
t _{d(on)}	Turn-On Delay Time		-	24	-	ns
t _r	Rise Time		-	45	- \	ns
t _{d(off)}	Turn-Off Delay Time	V _{CC} = 400 V, I _C = 40 A,	-	120	-	ns
t _f	Fall Time	$R_G = 10 \Omega$, $V_{GE} = 15 V$,	-	40	-	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 125°C	-	1.2	-	mJ
E _{off}	Turn-Off Switching Loss		-	0.69	-	mJ
E _{ts}	Total Switching Loss		-	1.89	-	mJ
Qg	Total Gate Charge		-	120	-	nC
Q _{ge}	Gate to Emitter Charge	$V_{CE} = 400 \text{ V}, I_{C} = 40 \text{ A},$ $V_{GF} = 15 \text{ V}$	-	14	-	nC
Q _{gc}	Gate to Collector Charge	GE 'GE	-	58	-	nC

Electrical Characteristics of the Diode T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Тур.	Max	Unit	
V _{FM}	Diode Forward Voltage	I _F = 20 A	T _C = 25°C	-	1.95	2.6	V
			T _C = 125°C	-	1.85	-	
t _{rr}	Diode Reverse Recovery Time	I _F =20 A, di _F /dt = 200 A/μs	$T_C = 25^{\circ}C$	-	45	-	ns
			T _C = 125°C	-	140	-	
Q _{rr}	Diode Reverse Recovery Charge		T _C = 25°C	-	75	-	nC
			T _C = 125°C	-	375	-	

Figure 1. Typical Output Characteristics

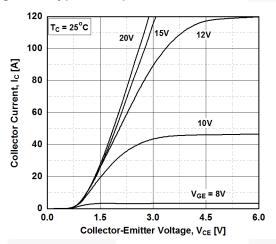


Figure 3. Typical Saturation Voltage Characteristics

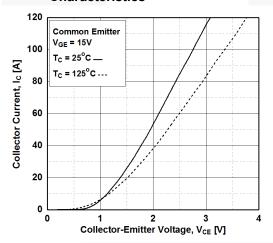


Figure 5. Saturation Voltage vs. Case
Temperature at Variant Current Level

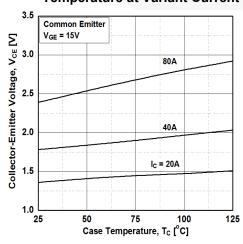


Figure 2. Typical Output Characteristics

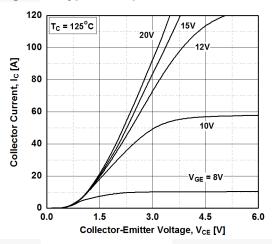


Figure 4. Transfer Characteristics

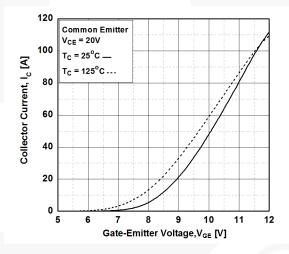


Figure 6. Saturation Voltage vs. V_{GE}

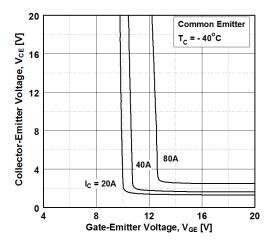


Figure 7. Saturation Voltage vs. V_{GE}

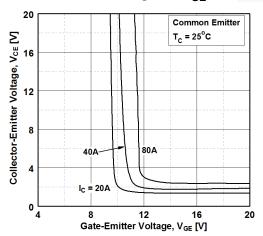


Figure 9. Capacitance Characteristics

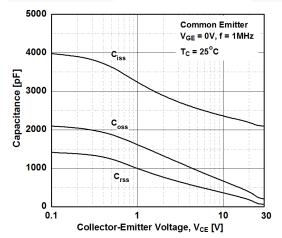


Figure 11. SOA Characteristics

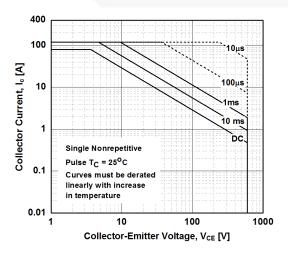


Figure 8. Saturation Voltage vs. V_{GE}

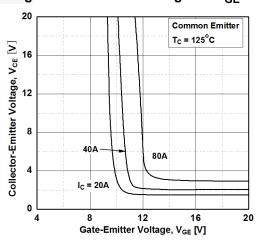


Figure 10. Gate charge Characteristics

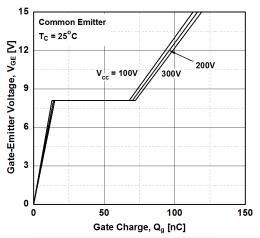


Figure 12. Turn-on Characteristics vs. Gate Resistance

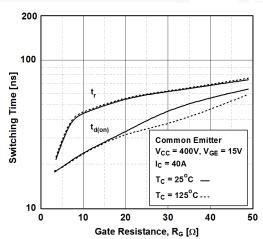


Figure 13. Turn-off Characteristics vs.
Gate Resistance

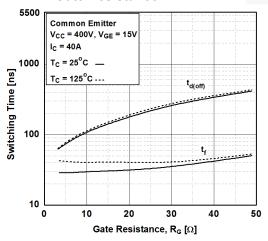


Figure 15. Turn-off Characteristics vs. Collector Current

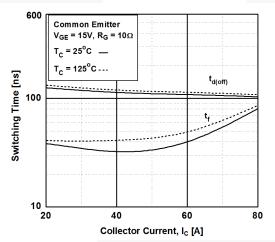


Figure 17. Switching Loss vs. Collector Current

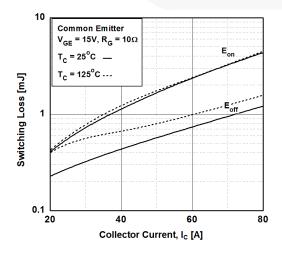


Figure 14. Turn-on Characteristics vs.
Collector Current

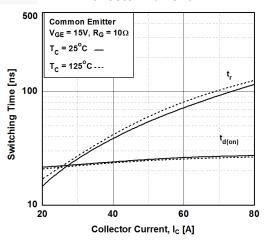


Figure 16. Switching Loss vs. Gate Resistance

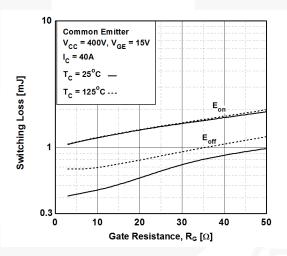


Figure 18. Turn off Switching SOA Characteristics

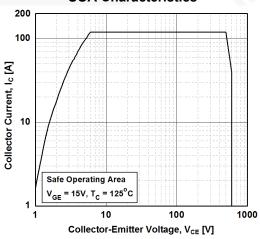


Figure 19. Forward Characteristics

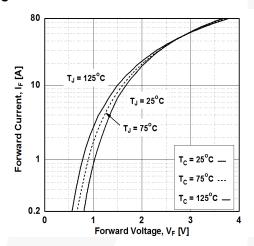


Figure 21. Stored Charge

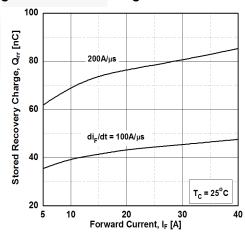


Figure 20. Reverse Current

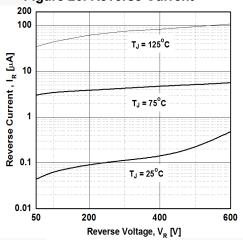


Figure 22. Reverse Recovery Time

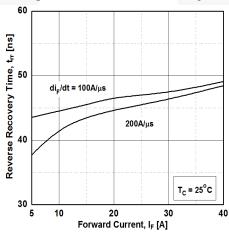
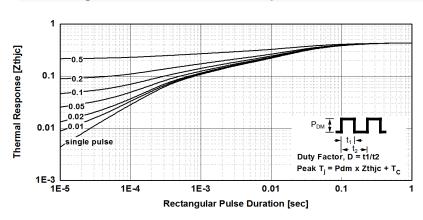
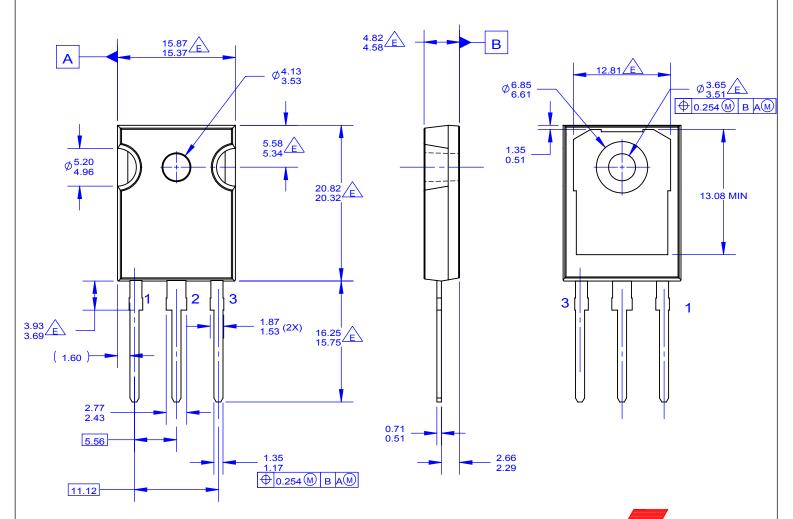


Figure 23. Transient Thermal Impedance of IGBT







NOTES: UNLESS OTHERWISE SPECIFIED.

- A. PACKAGE REFERENCE: JEDEC TO-247, ISSUE E, VARIATION AB, DATED JUNE, 2004.
- B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DRAWING CONFORMS TO ASME Y14.5 1994

DOES NOT COMPLY JEDEC STANDARD VALUE

F. DRAWING FILENAME: MKT-TO247A03_REV04

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdt/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and exp

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative